

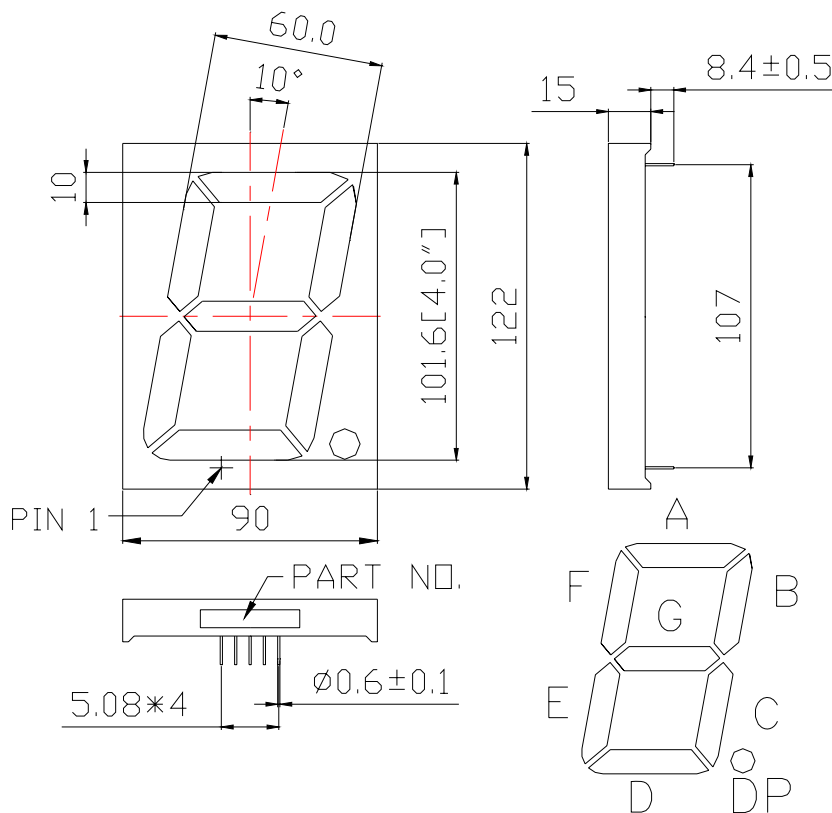
**WCN1-00D0SD-A11S****SPECIFICATION**

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei	Athena		
<b>REVISION RECORD</b>			



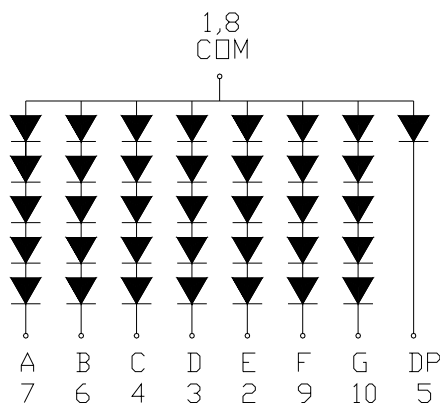
REVISION: A0

■ **Outer Dimension:**



**Note:** Unless otherwise stated , The tolerance is  $\pm 0.25$  mm.

■ **Circuit Diagram:**



■ **Pin Connection:**

PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Common Anode	6	Cathode B
2	Cathode E	7	Cathode A
3	Cathode D	8	Common Anode
4	Cathode C	9	Cathode F
5	Cathode DP	10	Cathode G

■ **Features:**

- High Reliability
- Color: Super Red
- Low Power Requirement
- Easy Assembly

■ **Description:**

- Single Digit LED Display
- Digit Height:101.6mm(4.0" )
- Black Face and Milky Segment

■ **Absolute Maximum Rating (Ta=25°C):**

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment/DP	P <sub>d</sub>	—	Red	325 / 65	mW
Forward Current Per Segment/DP	I <sub>F</sub>	—	Red	25	mA
Peak Forward Current Per Segment	I <sub>FP</sub>	1/10 Duty 10KHz	Red	100	mA
Reverse Voltage Per Segment/DP	V <sub>R</sub>	—	Red	25/5	V
Operating Temperature Range	Topr	—	—	-35~+85	°C
Storage Temperature Range	Tstg	—	—	-35~+85	°C

■ **Electrical/Optical Characteristics Rating(Ta=25°C)**

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	Per Segment	—	10.0	12.5	V
			DP		2.0	2.50	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =15V	Per Segment	—	—	100	μA
		V <sub>R</sub> =5V	DP				
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> =10mA	Per Segment	12.56	26	—	mcd
Wave Length	λ <sub>P</sub>	I <sub>F</sub> =20mA	Per Segment	—	660	—	nm
	λ <sub>D</sub>				640		
Spectral Line Half Width	△λ	I <sub>F</sub> =20mA	Per Segment	—	20	—	nm
Luminous Intensity Matching Ratio (Segment to Segment)	I <sub>v-m</sub>	I <sub>F</sub> =10mA	—	—	—	1.2:1	

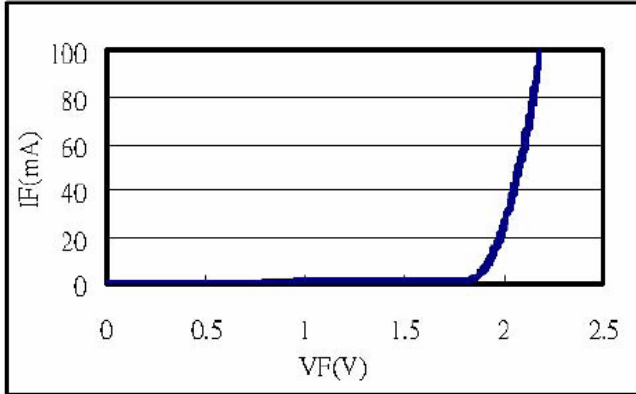
■ **Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)**

Rank	Symbol	Condition	Min	Max	Unit
M	M	I <sub>F</sub> =10mA	12.56	20.0	mcd
N	N	I <sub>F</sub> =10mA	20.0	32.0	mcd
O	O	I <sub>F</sub> =10mA	32.0	51.2	mcd

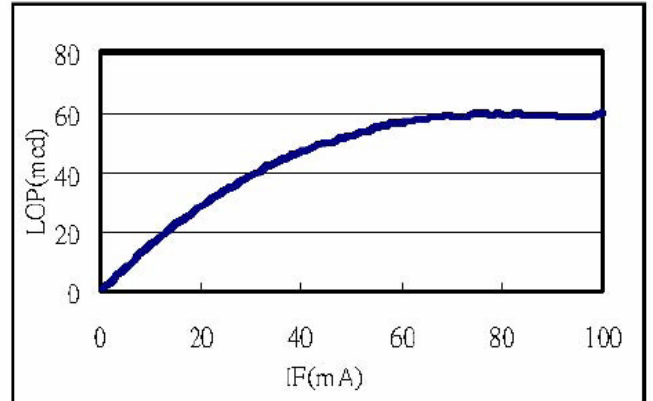
■ **Soldering Conditions: Soldering Temp. ≤+260°C, Soldering Time. ≤3sec.**  
 (at 2mm Distance from The Case of Reflector Edge)

■ **Typical Electro-Optical Characteristics Curve:**

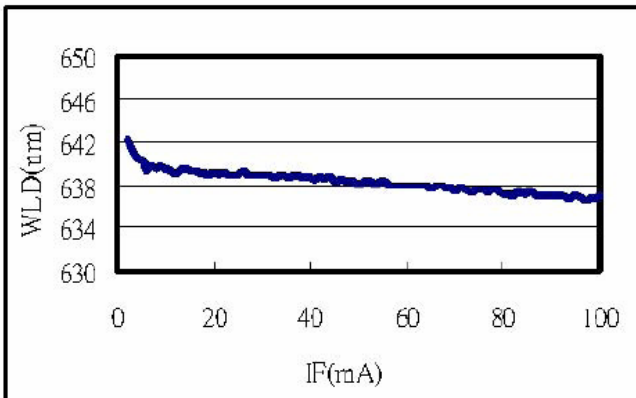
**Fig1. Forward Current vs. Forward Voltage:**



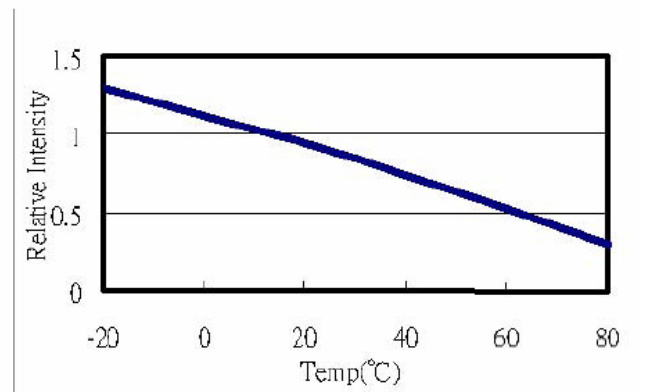
**Fig2. Forward Current vs. Relative Intensity:**



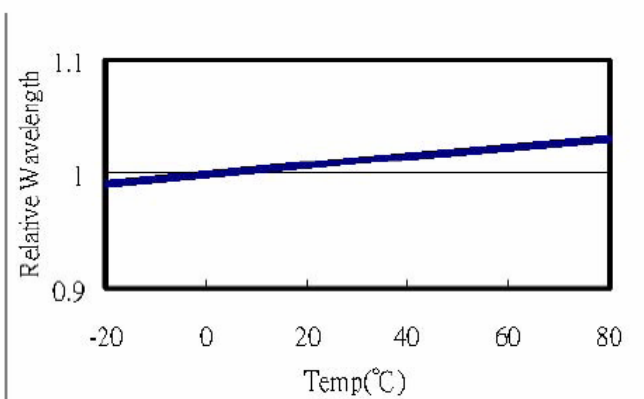
**Fig3. Forward Current vs. Relative Wavelength:**



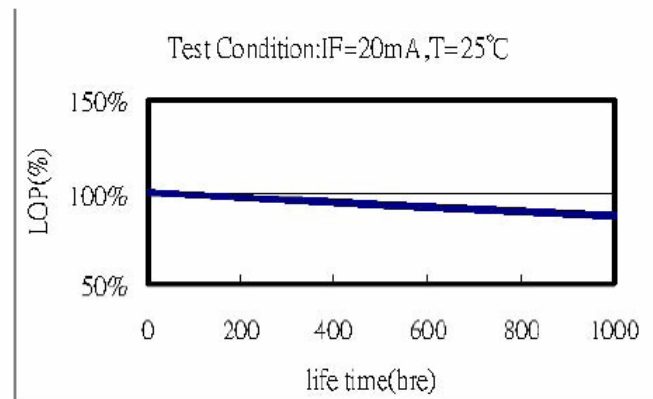
**Fig4. Temperature vs. Relative Intensity:**



**Fig5. Temperature vs. Relative Wavelength:**



**Fig6. Life Test at 20mA R.T. 1000hrs:**



## LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS $T_a$ = UNDER ROOM TEMPERATURE $I_F = I_F \text{ max}$
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY $T_a = 65 \pm 5^\circ\text{C}$ RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE $T_a = 85 \pm 5^\circ\text{C}$ (COB: $T_a = 65 \pm 5^\circ\text{C}$ ) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE $T_a = -35 \pm 5^\circ\text{C}$ TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION $85^\circ\text{C} \sim 25^\circ\text{C} \sim -35^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$ , $T_{\text{cold}}=-25^\circ\text{C}$ )
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES $85 \pm 5^\circ\text{C} \sim -35 \pm 5^\circ\text{C}$ 10min 10min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$ , $T_{\text{cold}}=-25^\circ\text{C}$ )
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE $T_{\text{SOL}}=230 \pm 5^\circ\text{C}$ DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING $T_{\text{SOL}}=260 \pm 5^\circ\text{C}$ DWELL TIME=10±1sec.

## Packing method A:

6 pcs / Red Expandable Polyethylene.

42 pcs / Box(360\*265\*255mm).

84 pcs / Carton(550\*380\*280mm).